

PCN Number:	20220615005.1	PCN Date:	June 16, 2022
Title:	Qualification of CFAB as an additional Fab site options for select LBC4 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Sep 16, 2022	Sample requests accepted until:	July 16, 2022*

***Sample requests received after July 16, 2022 will not be supported.**

Change Type:

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its CFAB fabrication facilities as an additional Wafer Fab option for the devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter
DL-LIN	LBC4	150 mm	CFAB	LBC4	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
CFAB	CU3	CHN	Chengdu

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20: 29:
 MSL 2 / 260C/1 YEAR SEAL DT
 MSL 1 / 235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: 0053317
 (20L) CSO: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

SN0405001PWPR	SN1407001PWPR	TPS40057PWPR	TPS63700DRCR
SN0805014PWPR	TPS40057PWP	TPS40057ZPWPR	TPS63700DRCT
SN0806054PWPR			

Qualification Report

Approve Date 6-May-2022

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ24085DRCR	QBS Process Reference: TLC5970RHPR	QBS Package Reference: UCC27201AQDMKRQ1
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
HBM	ESD - HBM	3000 V	1/3/0	-	-
HBM	ESD - HBM	2000 V	-	3/9/0	-
CDM	ESD - CDM	1500 V	1/3/0	-	-
CDM	ESD - CDM	500 V	-	3/9/0	-
LU	Latch-up	(per JESD78)	1/6/0	3/18/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device BQ24085DRCR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

Qualification Report

Approve Date 6-May-2022

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS63700DRCR	QBS Process Reference: TLC5970RHPR	QBS Package Reference: TPS2559DRCR
HTOL	Life Test, 125C	1000 Hours	1/77/0	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	2/154/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
uHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	-	-
HBM	ESD - HBM	2000 V	-	3/9/0	-
CDM	ESD - CDM	1000 V	1/3/0	-	-
CDM	ESD - CDM	500 V	-	3/9/0	-
LU	Latch-up	(per JESD78)	1/6/0	3/18/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	-
MQ	Assembly MQ	Per Site Specifications	Pass	Pass	Pass

- QBS: Qual By Similarity

- Qual Device TPS63700DRCR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

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Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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